

U.S. Pat. Appl. 10/522,785

Amendments to the Abstract:

ABSTRACT

Please replace the abstract that appears on page 8 of the specification with the following revised abstract which is submitted on a separate sheet.

Abstract

~~The invention relates to an~~ An electronics housing [(1)] with a circuit board [(4)] in the interior [(2)] of the electronics housing [(1)], fitted with electronics components [(5, 6)] on at least one first surface, said first surface facing a first wall [(3)] of the electronics housing and the interior is filled with a thermally conducting sealing mass [(10)], at least between the first surface of the circuit board [(4)] and the first wall [(3)]. According to the invention, local overheating on the external housing surfaces may be avoided whereby a planar heat dissipater [(7)] is arranged in the sealing mass, between the circuit board and the first wall, which has a higher specific heat conductivity than the sealing mass, whereby inhomogeneous temperature distributions along the surfaces of the first wall are reduced.